

Title (en)  
UNIT AND PRODUCTION OF A UNIT

Title (de)  
BAUGRUPPE SOWIE HERSTELLUNG EINER BAUGRUPPE

Title (fr)  
MODULE ET FABRICATION D'UN TEL MODULE

Publication  
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Application  
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Abstract (en)  
[origin: WO2009019091A1] The invention relates to a unit (1) having a substrate (5) and at least one component (3) mounted thereon by sintering using a sintering agent (8), particularly sintering paste. According to the invention, the sintering agent (8) is disposed in a depression (7) of the substrate (5) at least partially receiving the component (3). The invention further relates to a method for producing a unit having a substrate and at least one component mounted thereon by sintering using a sintering agent, particularly sintering paste. According to the invention, the sintering agent is placed in a depression of the substrate at least partially receiving the component.

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Citation (search report)  
See references of WO 2009019091A1

Citation (examination)  
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• JP 2005101353 A 20050414 - TOSHIBA CORP  
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• JP H0945814 A 19970214 - NEC CORP  
• JP H0547810 A 19930226 - FUJITSU MIYAGI ELECTRON KK

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